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(71) Applicant(s)

Hewlett-Packard Company  
(Incorporated in USA - Delaware)  
3000 Hanover Street, Palo Alto,  
California 94304, United States of America

(72) Inventor(s)

Jeffery S Hess

(74) Agent and/or Address for Service

Carpmaels & Ransford  
43 Bloomsbury Square, LONDON,  
WC1A 2RA, United Kingdom

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Other: Online: EPODOC JAPIO WPI

(54) Abstract Title

Substrate and method of forming substrate for fluid ejection device

(57) A method of forming an opening (50/50'/150/150') through a substrate (60) includes etching into the substrate from a first side (62) so as to form a first portion (52/152) of the opening, etching into the substrate from a second side (64) opposite the first side so as to form a second portion (54/154) of the opening, continuing etching into the substrate from at least one of the first side and the second side toward the other of the first side and the second side so as to communicate the first portion and the second portion of the opening, and etching into the substrate from an interface (55/155) between the first portion and the second portion of the opening, including etching toward the second side of the substrate and forming a third portion (56/56'/156) of the opening. There is also a substrate (60) for a fluid ejection device having a fluidic channel (50) formed by the method described above. The fluid ejection device may be an inkjet printhead.

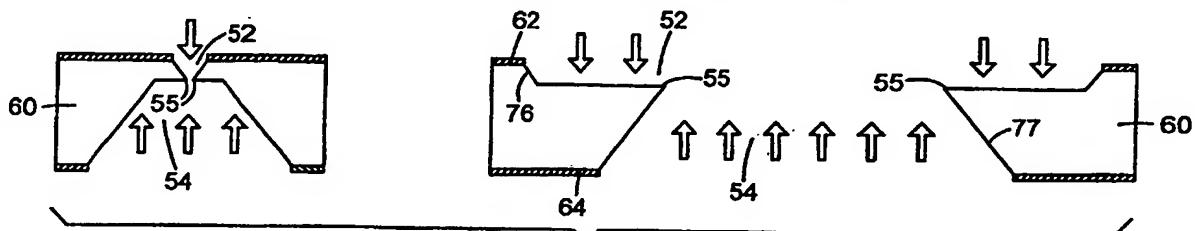
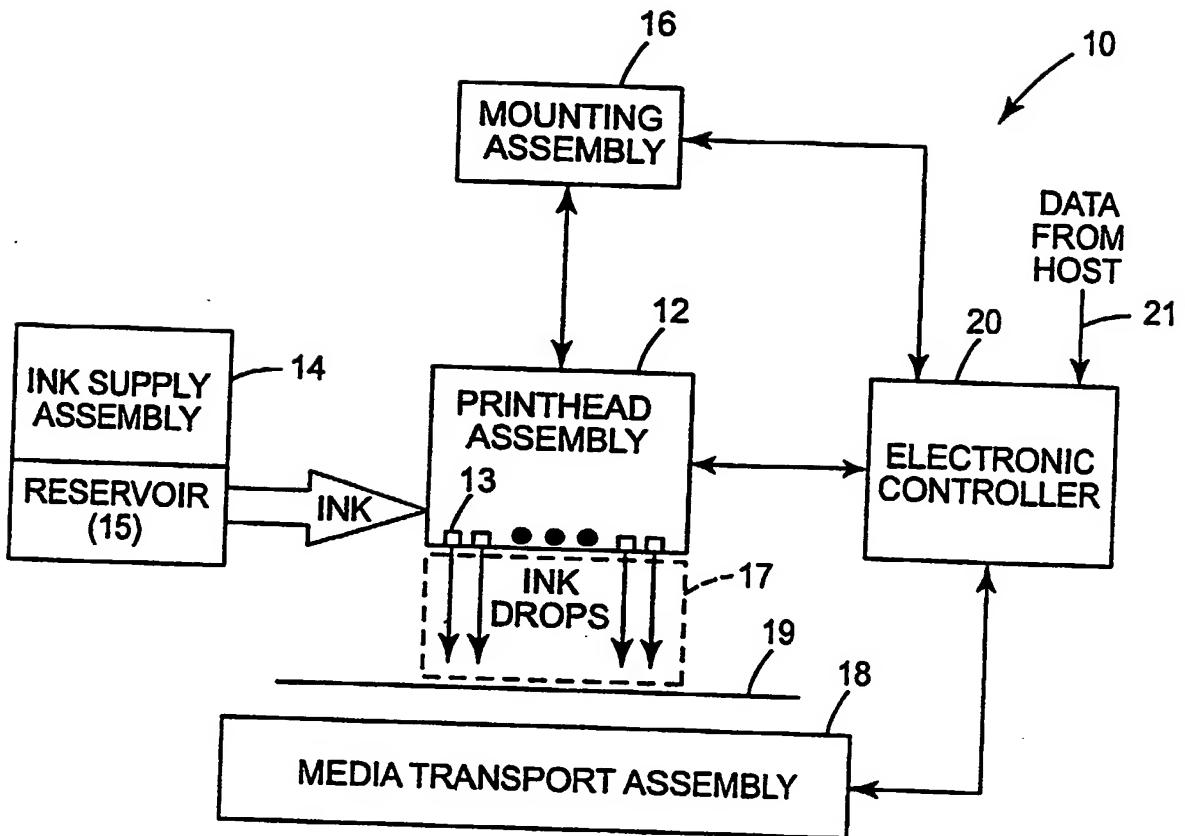
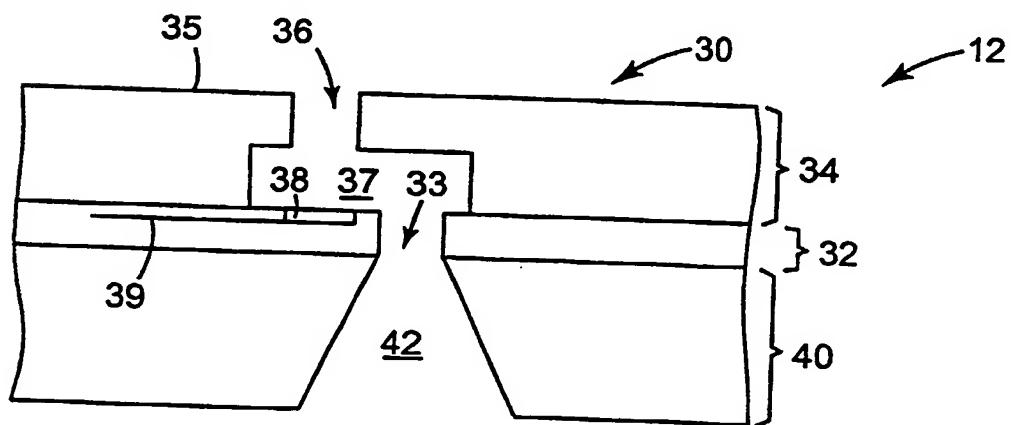
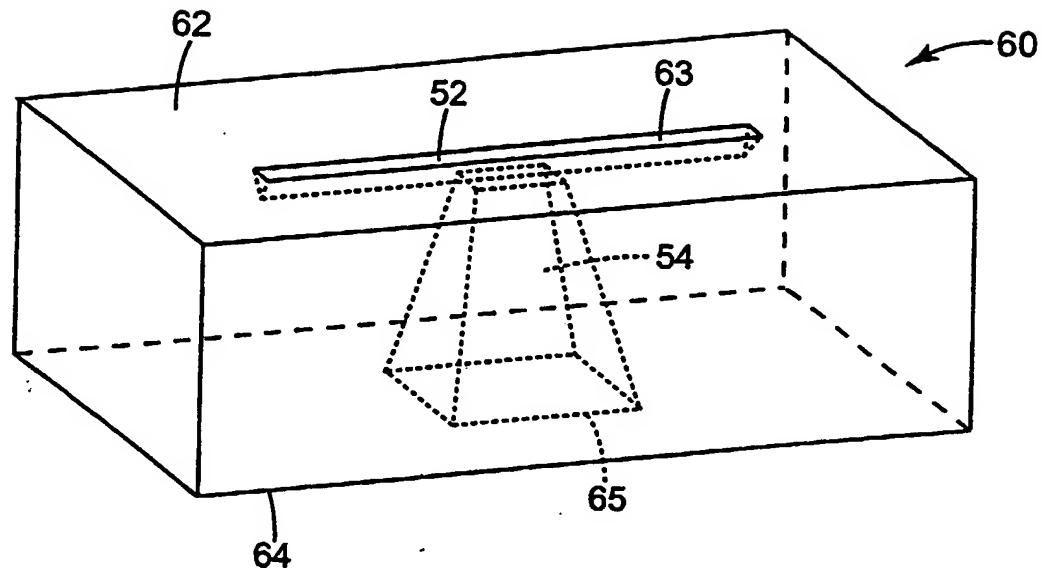


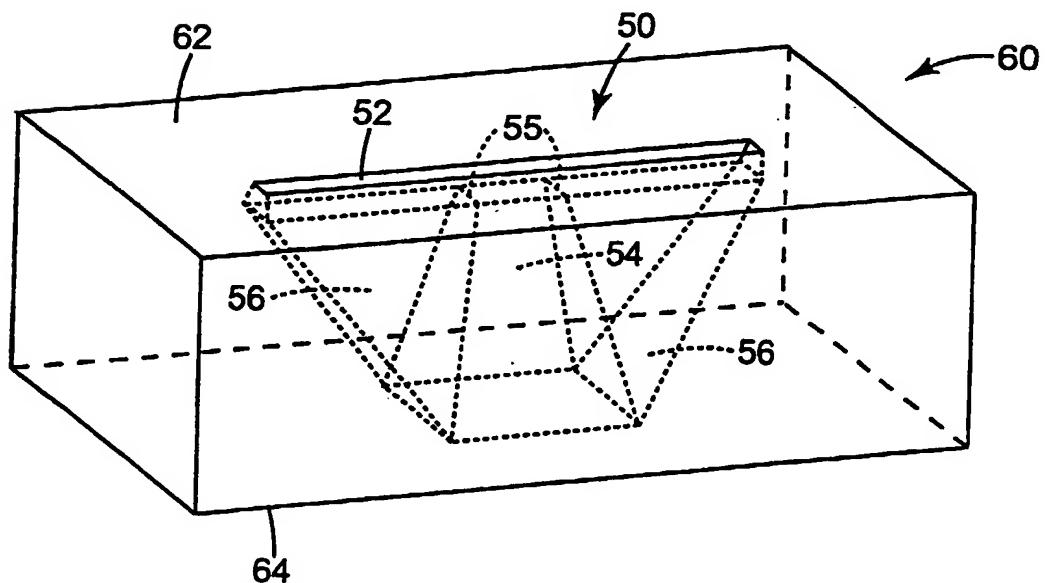
Fig. 5C

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**Fig. 1****Fig. 2**

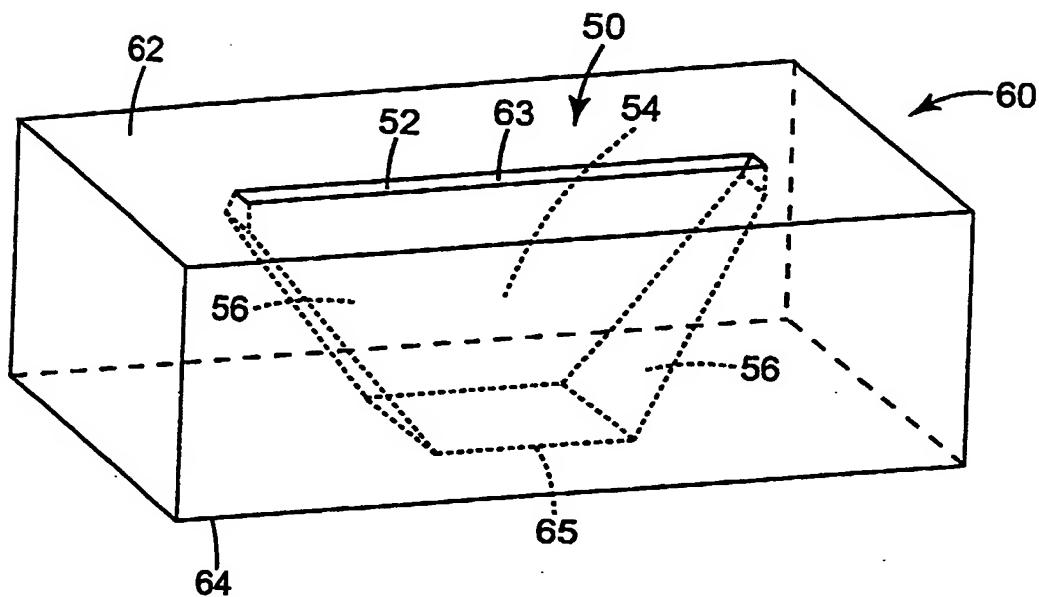


***Fig. 3A***

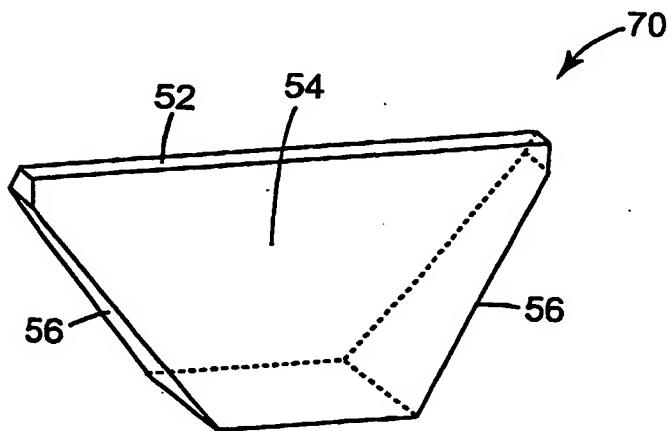


***Fig. 3B***

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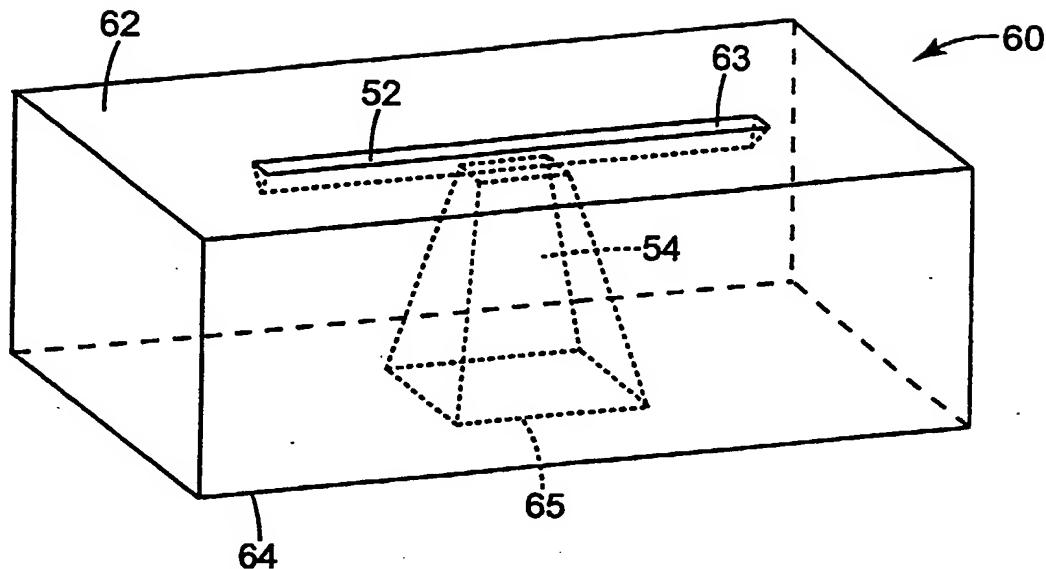


***Fig. 3C***

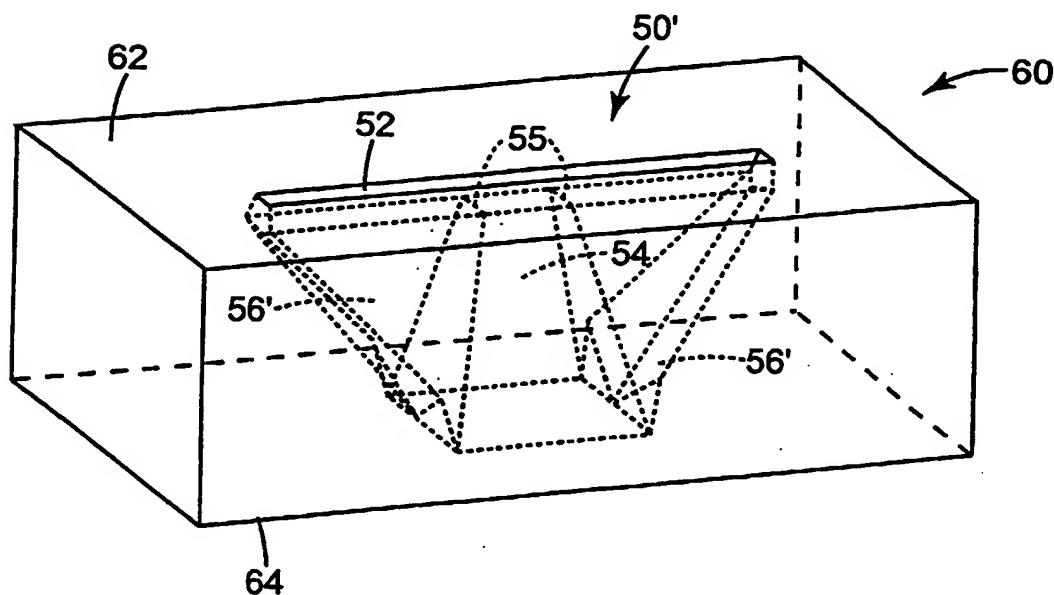


***Fig. 3D***

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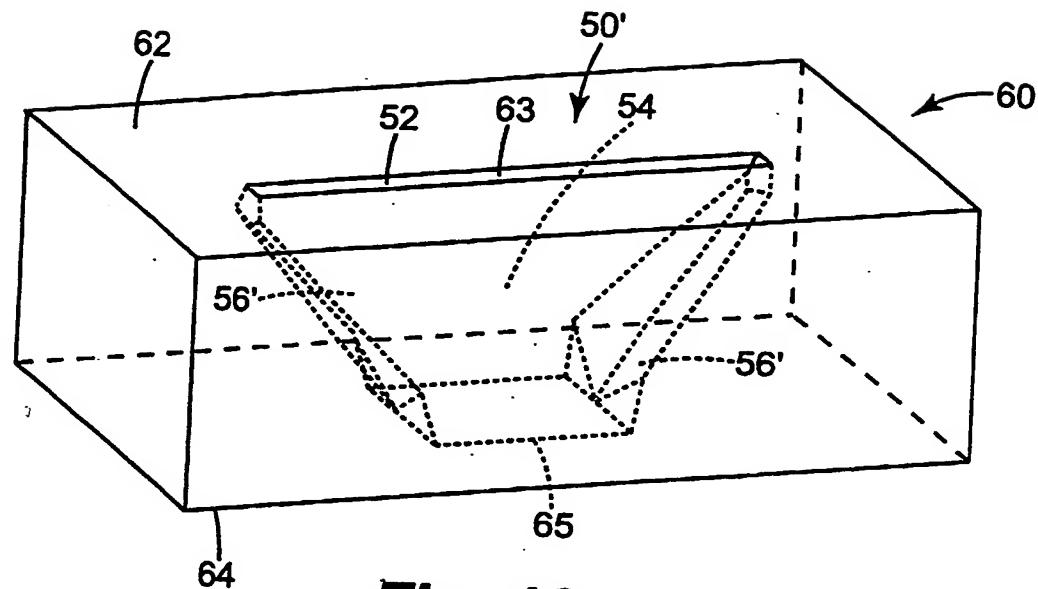


*Fig. 4A*

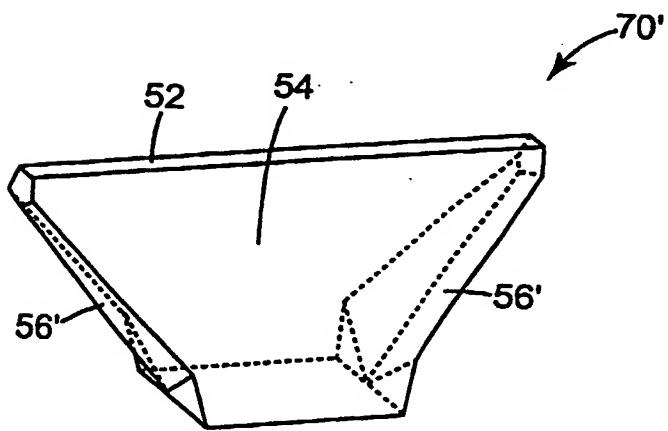


*Fig. 4B*

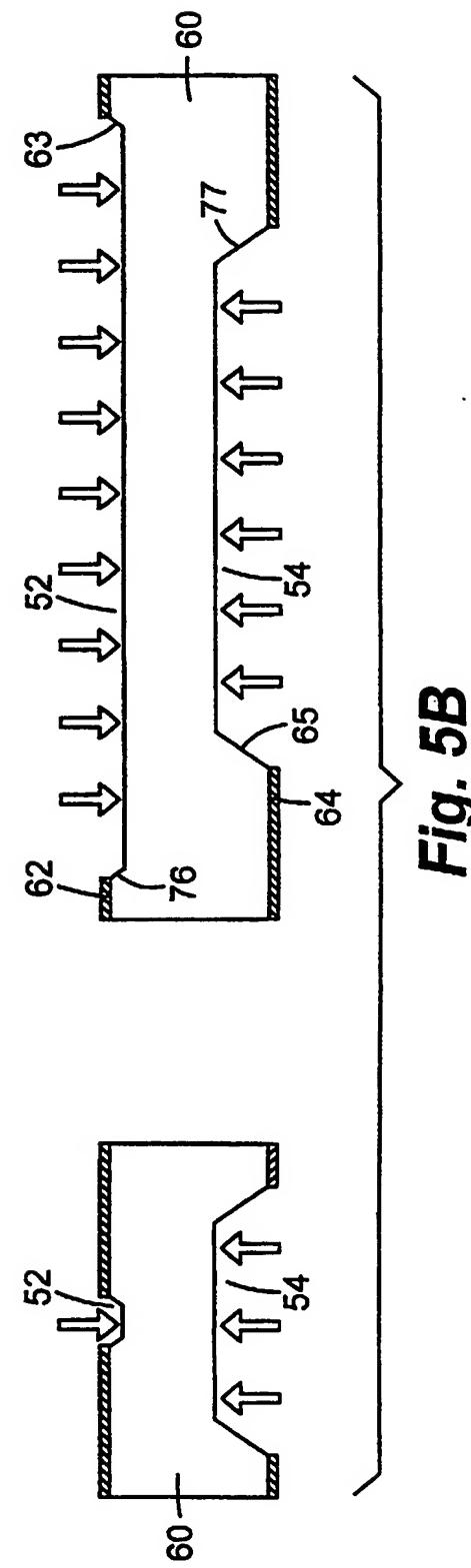
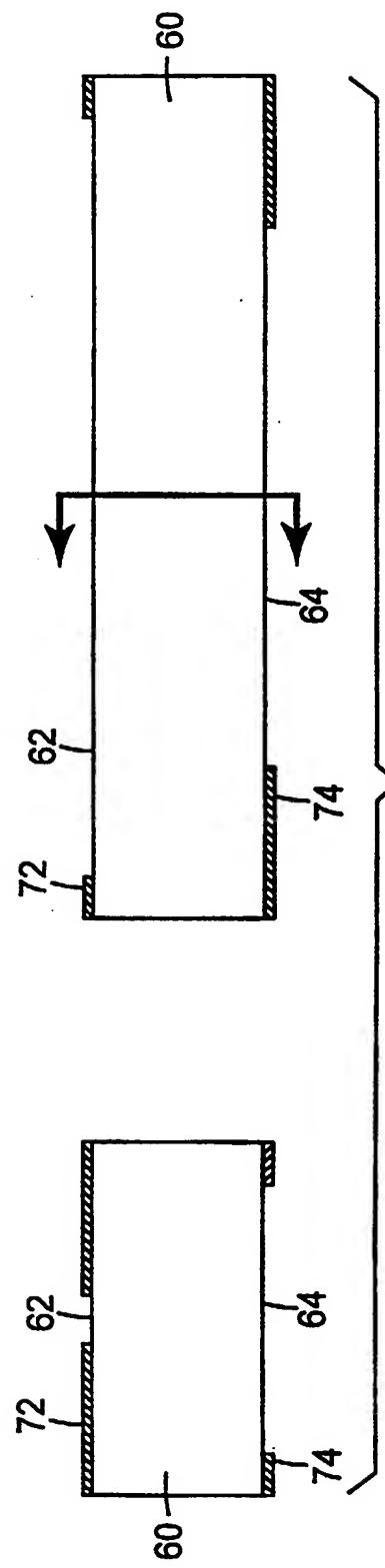
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***Fig. 4C***



***Fig. 4D***



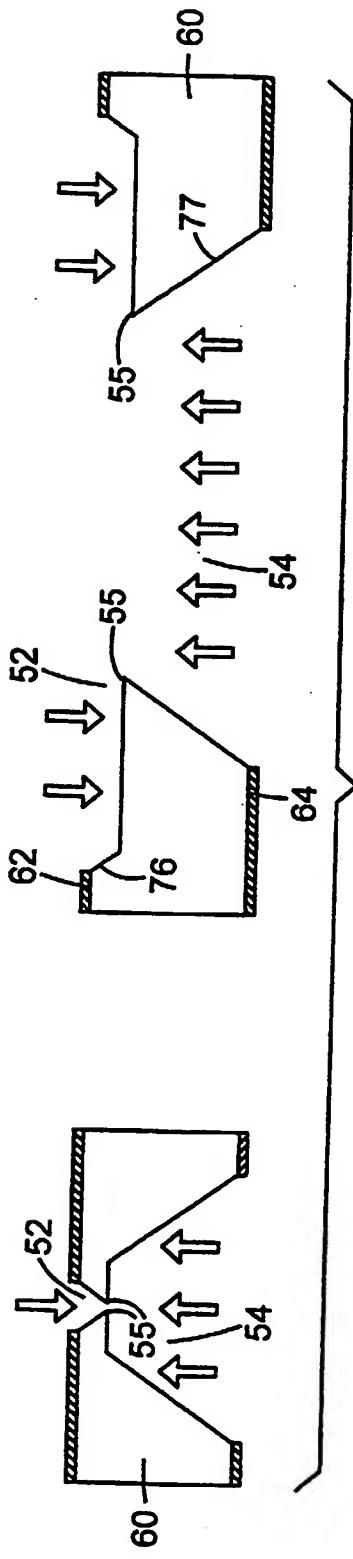


Fig. 5C

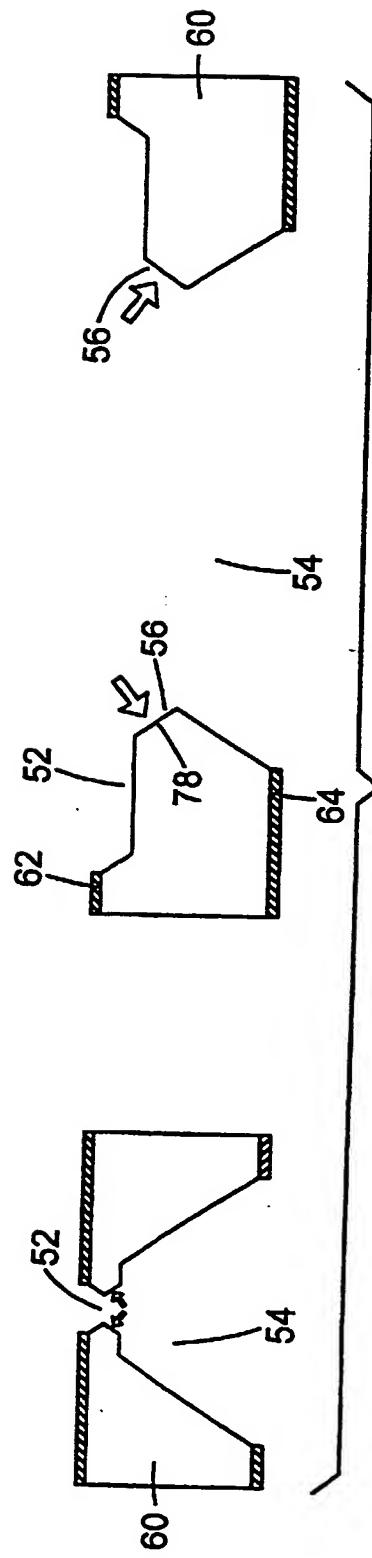
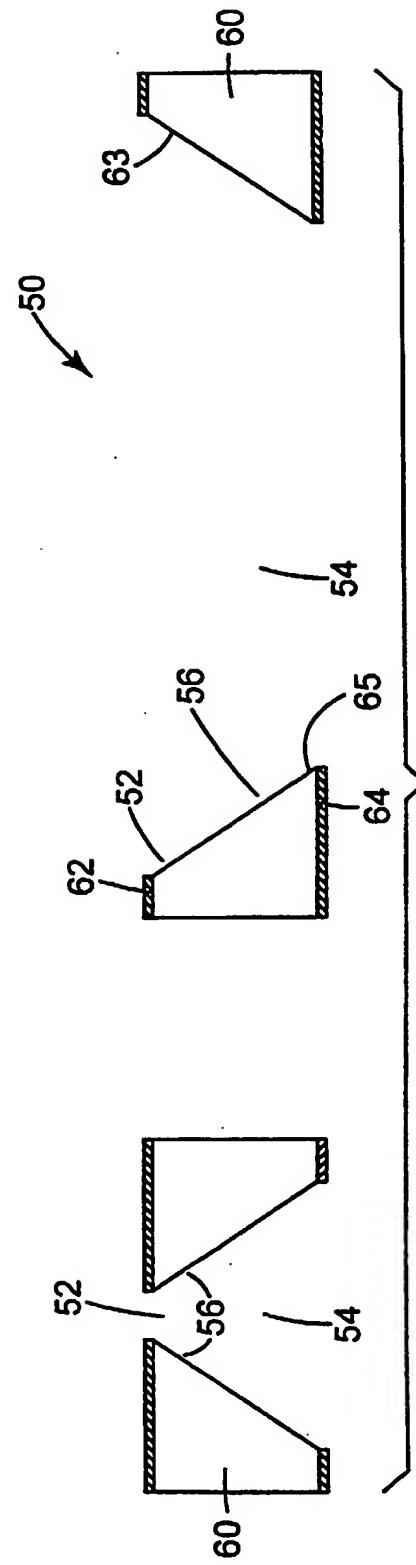
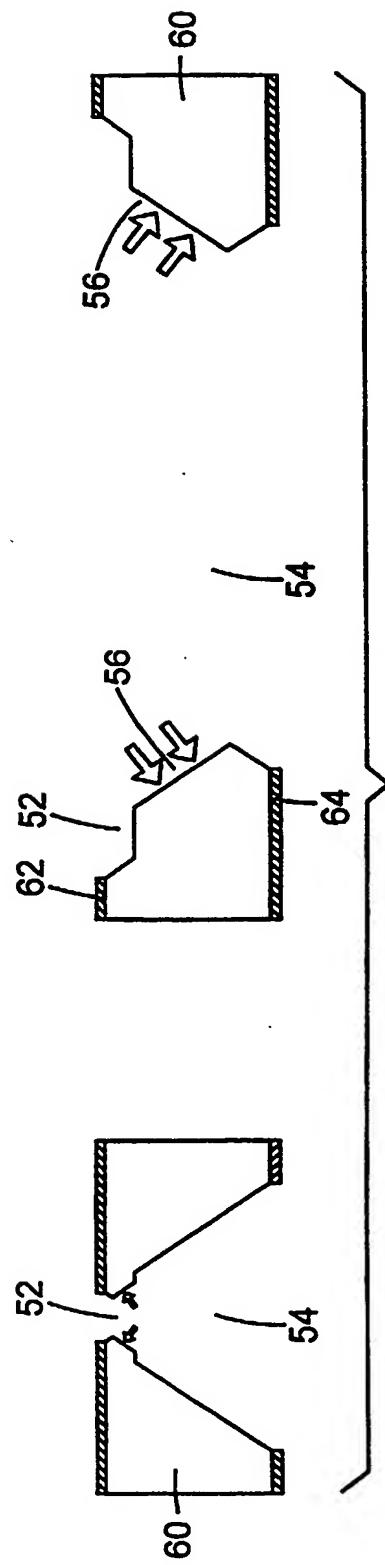


Fig. 5D



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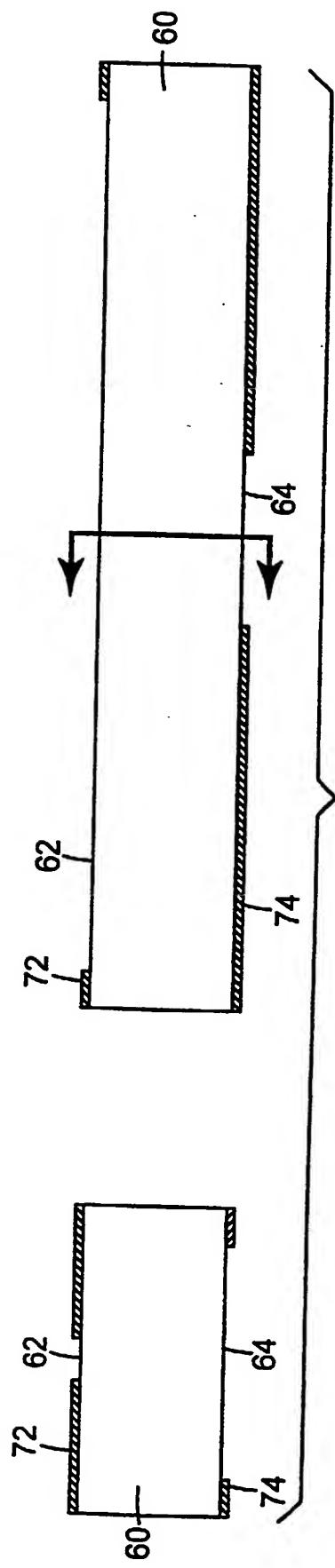


Fig. 6A

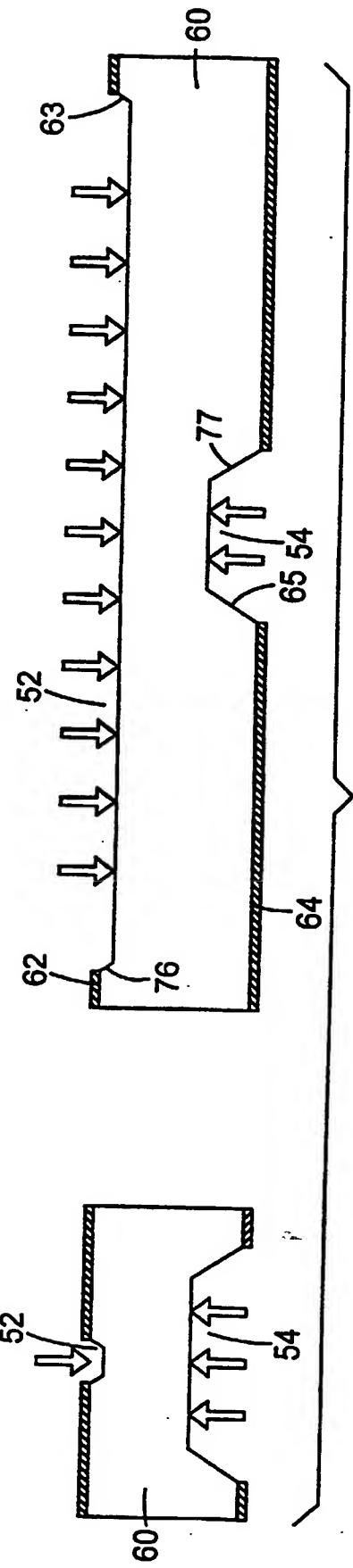


Fig. 6B

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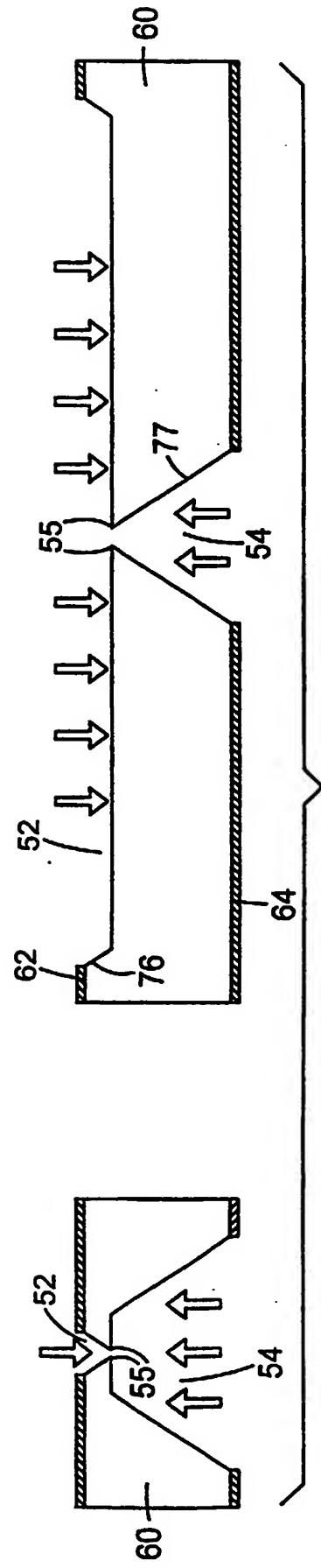


Fig. 6C

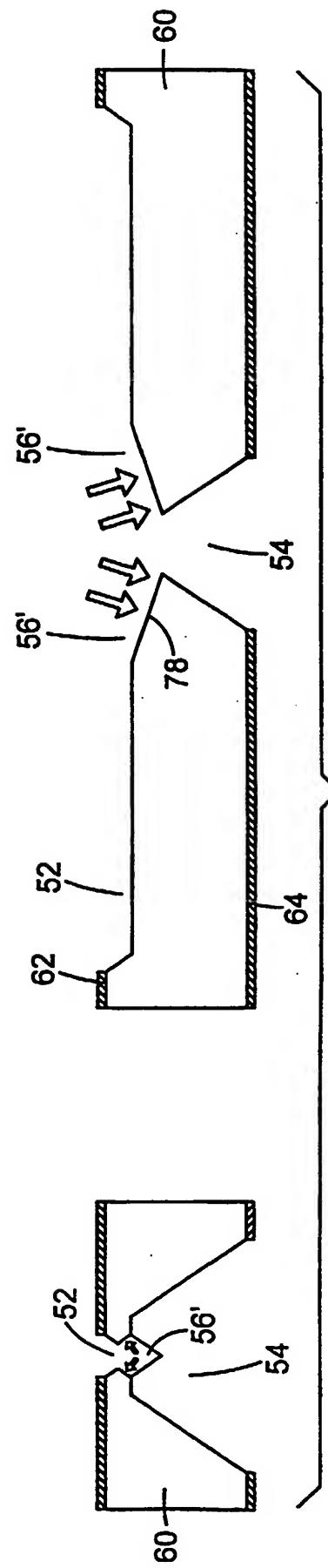


Fig. 6D

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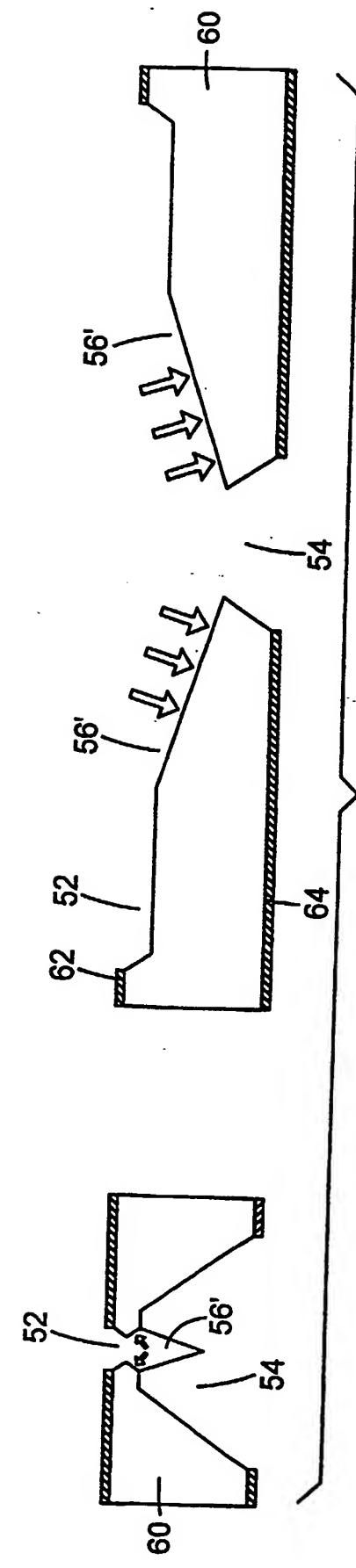


Fig. 6E

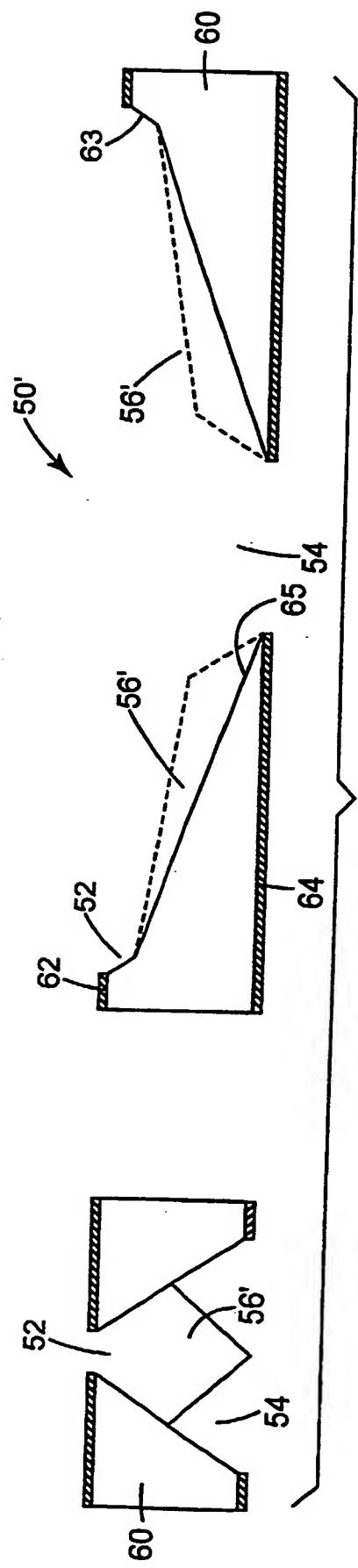
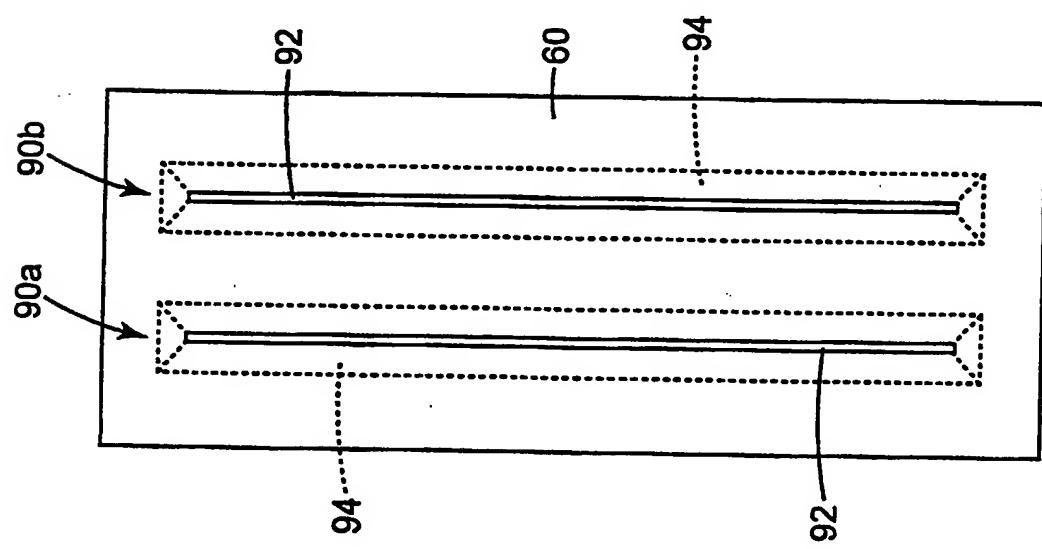
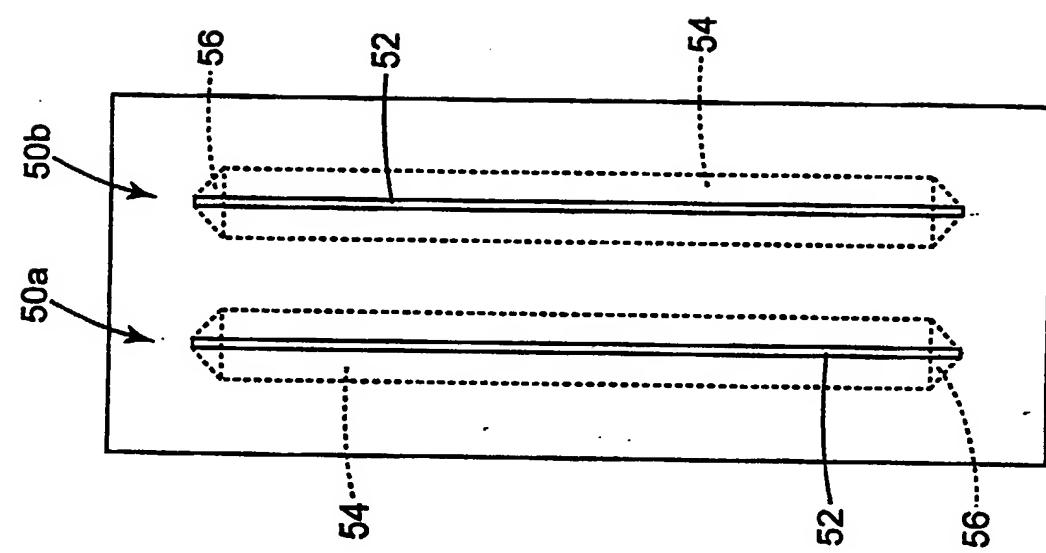


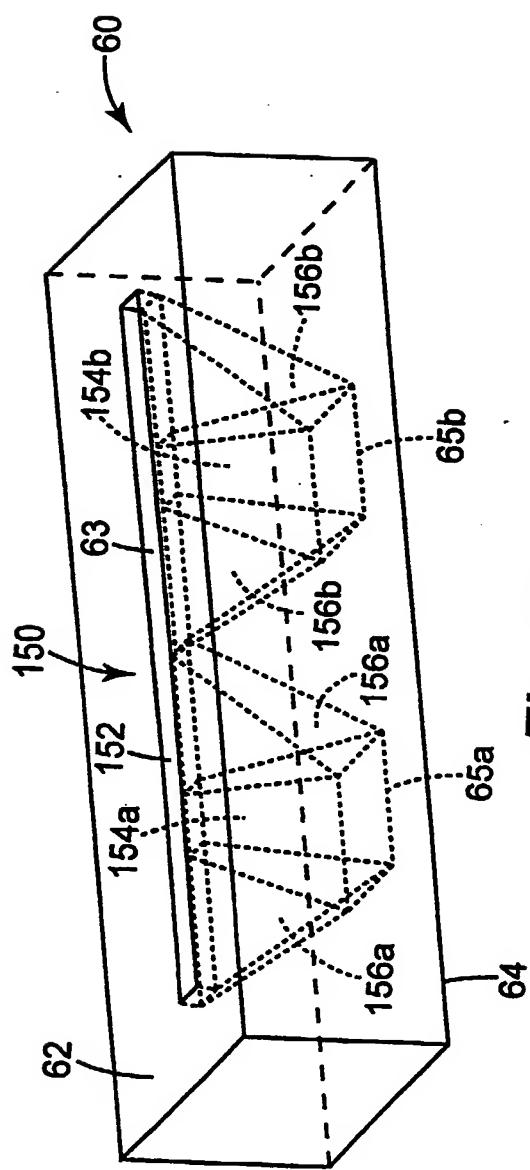
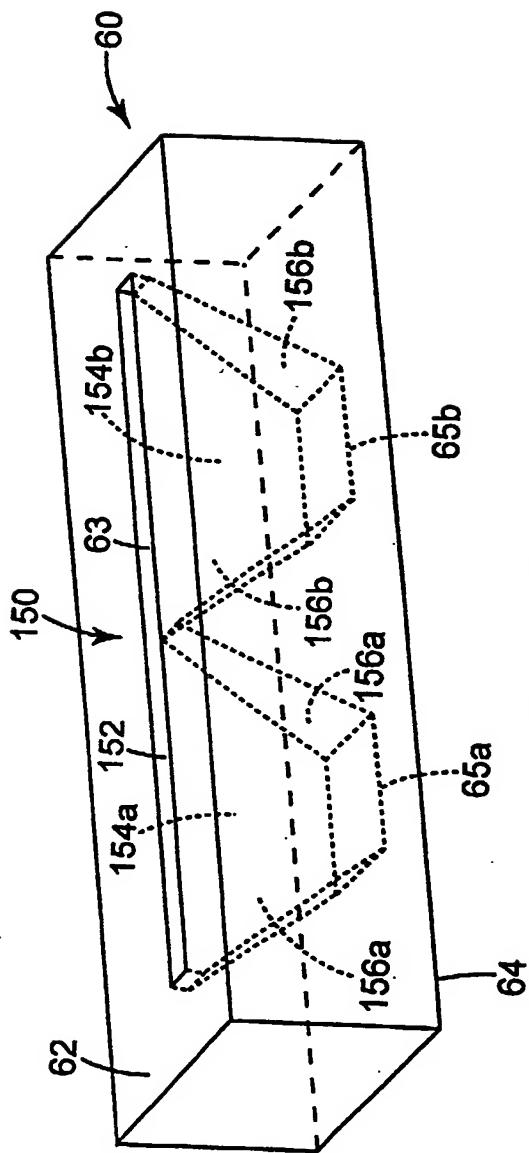
Fig. 6F

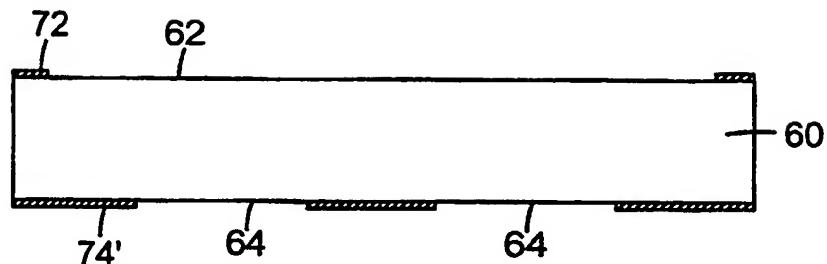
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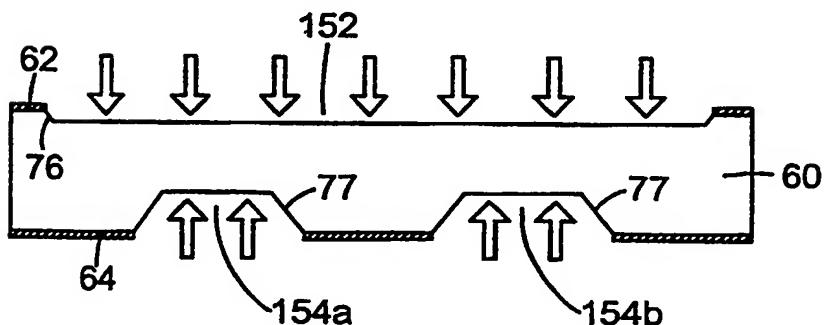
**PRIOR ART**  
**Fig. 7**

**Fig. 8**

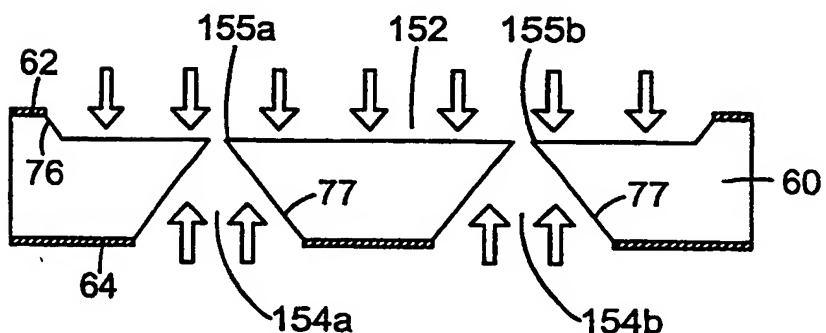
*Fig. 9A**Fig. 9B*



**Fig. 10A**

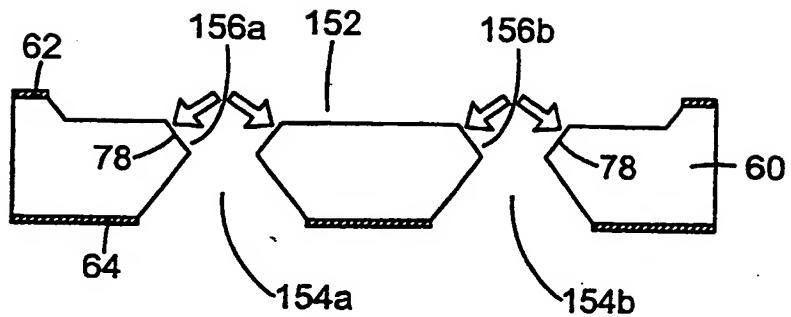


**Fig. 10B**

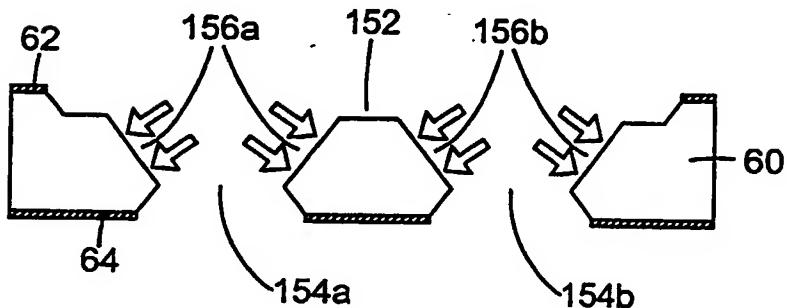


**Fig. 10C**

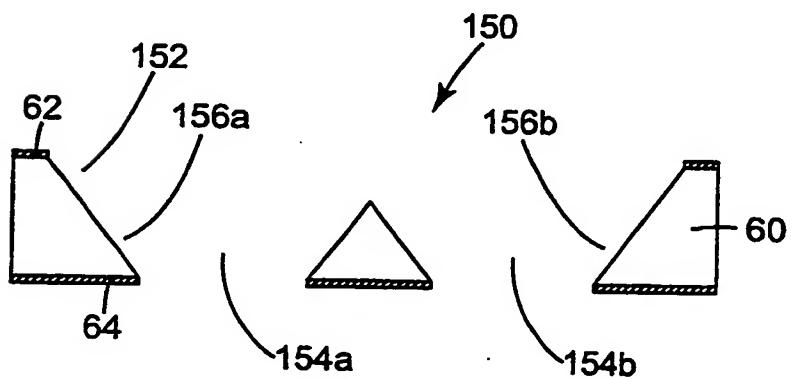
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**Fig. 10D**



**Fig. 10E**



**Fig. 10F**



Fig. 11B

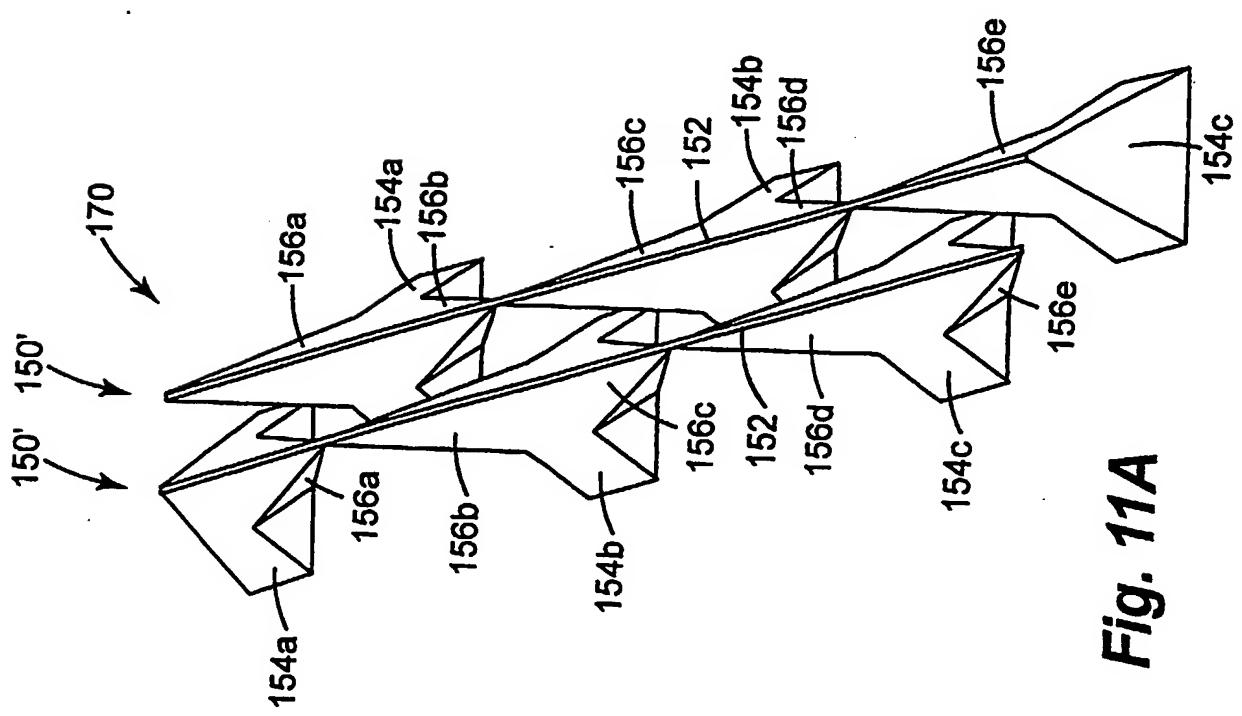


Fig. 11A

